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CCS L56

SJ

INDUSTRY STANDARD OF THE PEOPLE'S REPUBLIC OF CHINA

SJ 21452-2018

Integrated circuit ceramic package, chip adhesive bonding, technical requirements

集成电路陶瓷封装 芯片胶粘接装片工艺技术要求

(English Translation)

Issued by: Ministry of Industry and Information Technology

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1 Foreword

SJ 21452-2018 is issued by Ministry of Industry and Information Technology.

The SJ prefix, without a suffix, marks a mandatory standard: within its scope, compliance is required.

The document runs to 8 pages in English translation.

2 Scope Preview

SJ 21452-2018 is filed under Chinese Standard Classification L56, in the field of electronic components and information technology.

This catalogue holds 1,191 other SJ standards without an ICS number.

In this catalogue, SJ standards carry edition years from 1965 to 2021.

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3 About this standard

Sector: Electronics Industry Standard

Issued by: Ministry of Industry and Information Technology

English translation: about 8 pages (approximate)

Chinese original: about 12,154 characters

4 Related standards

Standards on related subjects:

SJ/T 11890-2023 - Design requirement of energy conservation for LED displays

SJ/T 11891-2023 - Energy efficiency measurement method for LED displays

GB/T 35010.6-2018 - Semiconductor die products -- Part 6: Requirements for concerning thermal simulation

SJ 21450-2018 - Integrated circuit ceramic package original film thinning process technical requirements

SJ 21449-2018 - Integrated circuit ceramic package pre-installation inspection requirements

SJ 21448-2018 - Integrated circuit ceramic package pre-bonding inspection requirements

5 Classification and status

Chinese Standard Classification (CCS): L 56

Prefix SJ: mandatory standard.

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